

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.1

*Applicant Information:*Inventor 1:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Masuo
Family Name: KONDO
City of Residence: Ibaraki-shi, Osaka
Country of Residence: JP
Address-1 of Mailing Address: 1-10-16-330, Mitsukeyama
Address-2 of Mailing Address:
City of Mailing Address: Ibaraki-shi, Osaka
State of Mailing Address:
Postal Code of Mailing Address: 567-0035
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Inventor 2:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Fumiaki
Family Name: KIKUI
City of Residence: Minamikawachi-gun, Osaka
Country of Residence: JP
Address-1 of Mailing Address: 1-13-15, Satsukinohigashi, Mihara-cho
Address-2 of Mailing Address:
City of Mailing Address: Minamikawachi-gun, Osaka
State of Mailing Address:
Postal Code of Mailing Address: 587-0032
Country of Mailing Address: JP

Phone:

Fax:

E-mail:

Correspondence Information:

Customer Number:

22204

22204

Application Information:

Title of Invention: SOLDER BALL, METHOD OF MAKING THE SAME, AND
METHOD OF MAKING SEMICONDUCTOR INTERCONNECT
STRUCTURE

Application Type: regular, utility

Attorney Docket Number: 743421-82

Botanic Information:

Publication Information:

Suggested Figure for Publication -

Suggested Classification -

Suggested Technology Center -

Total Number of Drawing Sheets -

Representative Information:

practitioner(s) at Customer Number:

22204

22204

as our attorney(s) or agent(s) to prosecute the application identified above, and to transact
all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of JP application number PCT/JP03/12183, filed 2003-09-24, now
Pending.

Foreign Priority Information:

Doc.No:2002-283301; Country - JP; Date: 2002-09-27 us-priority-claimed

Doc.No:2002-291187; Country - JP; Date: 2002-10-03 us-priority-claimed

Assignee Information:**Assignee 1:**

Organization Name: Neomax Materials Co., Ltd.

Address-1 of Mailing Address: 2-19-1, Minamisuita

Address-2 of Mailing Address:

City of Mailing Address: Suita-shi, Osaka

State of Mailing Address:

Postal Code of Mailing Address: 564-0043

Country of Mailing Address: JP

Phone:

Fax:

E-mail: